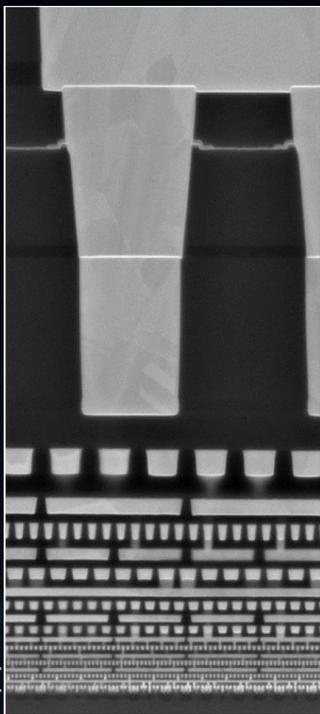




Making Next-Gen Microchips a Reality!

Interconnect Scaling Has Hit a Wall

2um Human Hair: ~70um



Transistor shrinks

Image from Intel – 18-layer
metal stack

Copper interconnect resistance skyrockets below 10 nm – stopping chip miniaturization!

At these scales, protective barriers occupy up to ~70% of the wire's area – **leaving little room for the interconnect.**

Next-gen semiconductor advances are slowing down, threatening innovation in AI, mobile and high-performance computing.

The Solution

Our product has been validated by



>25%
Lower Resistance:
Superior electrical conduction

No Barrier Required:
Simplifying the manufacturing
process

**Seamless
Process Integration:**
Engineered for Atomic Layer
Deposition

Our new material enables the first 1nm node
generation & beyond!

Business Model

Direct sale & Long-term supply agreements
of specialty metal precursor materials

**Primary
Revenue**

Semiconductor equipment
manufacturers
& Foundries/IDMs

Custom Development Fees
Milestone Payments

**Additional
Upside**

Customers

First client: **Applied
Materials**

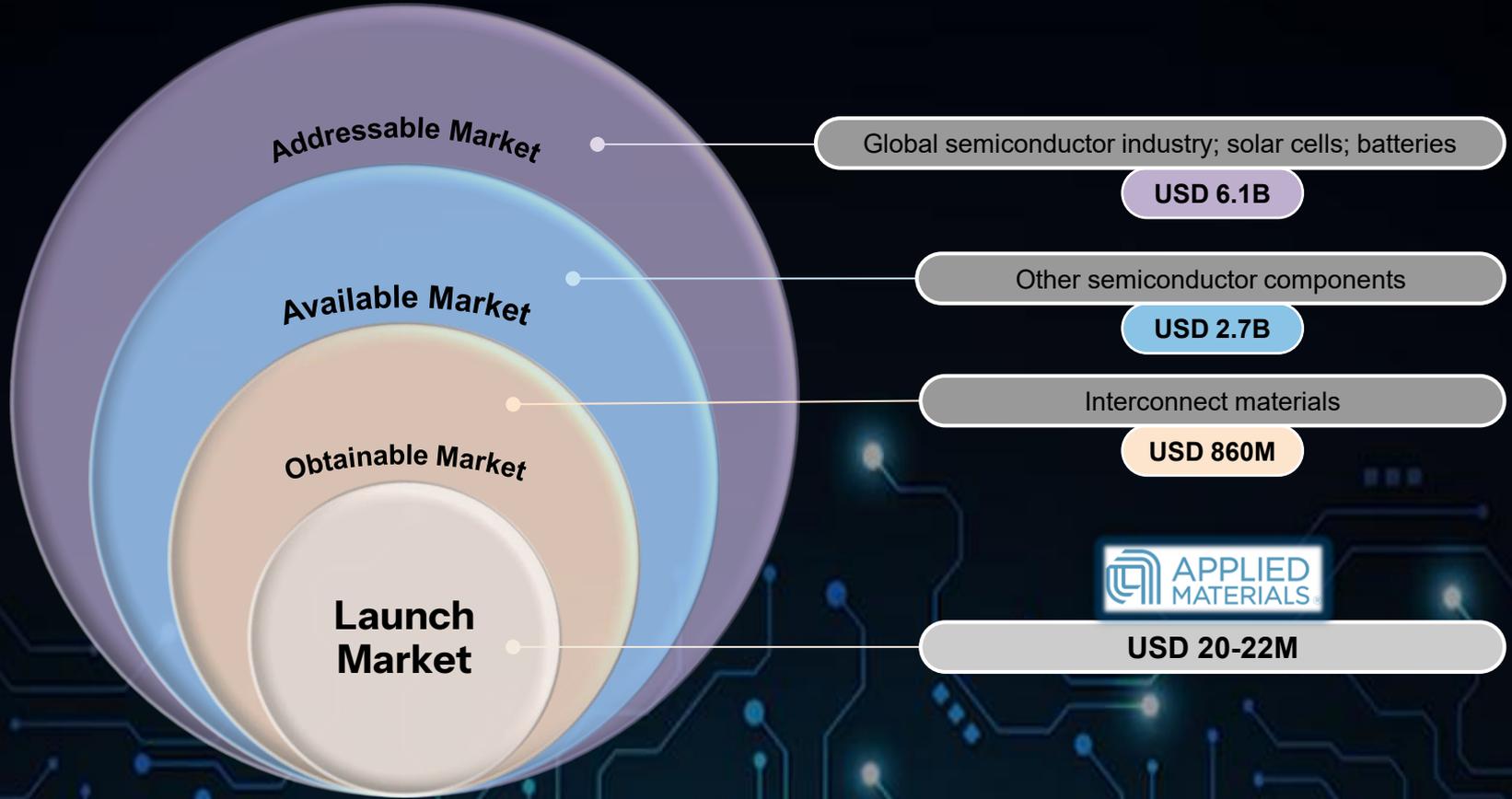
~40-70% at scale

Gross Margin

Pricing

USD 75-150/g
(volume & purity dependent)

Market Size



Industry Traction



Equipment Manufacturer

Total Contract Value: USD 20-22M
(2-Year Equipment Qualification)

- Requested long-term collaboration
- Expressed interest in investing
- Market entry support into semiconductor foundries



Chemical Manufacturers

Total Contract Value: USD 285M
(last year: USD 187M)

- Interest in licensing & contract manufacturing deals
- Exploring joint development opportunities
- NDAs in progress



Global Leader Niobium Mining

Total Contract Value: < USD 20M

- Research collaboration initiated
- Beyond interconnect applications
- Potential investor

Our Competitors

Features	EXISTING TECHNOLOGY (Copper)					 PRODUCT-A
Liquid Chemicals	✗	✗	✗	✗	✗	✓
High Purity	✓	✓	✓	✗	✗	✓
Less Hazardous	✗	✗	✗	✗	✗	✓
No barrier	✗	✓	✓	✓	✓	✓
Enables next-gen microchips	✗	✗	✗	✗	✗	✓

Meet the Team



Dr Beatriz Ferraz
Co-founder, CEO

Scaled materials from lab to pilot production at Dyson.

6 years of experience in Carbon Materials and Batteries.



Dr Sara Aguiar
Co-founder, CSO

Synthetic Chemist with 10 years of experience in organometallic and coordination chemistry for various applications, including Semiconductors.



Edward Teoh
Co-founder, COO

Co-Founder of Motivo, Inc

20+ years of Industrial Experience in Semiconductor Industry. From IC Design to Technology Development, PDK and EDA.



Associate Professor Huynh Han Vinh
Scientific Advisor

Organometallic Synthesis Expert with 20+ Years of Experience.

Research Group Leader.



Funding & Use of Funds

Raising
USD 2.7M
Pre-Seed
Funding

Runway: 1.5 years

Revenue: \$ 322M in 5 Years

Production Scale-up: ~70x

32%

Supply Chain Setup

8%

Support Customer's Engineering
and Process Validation

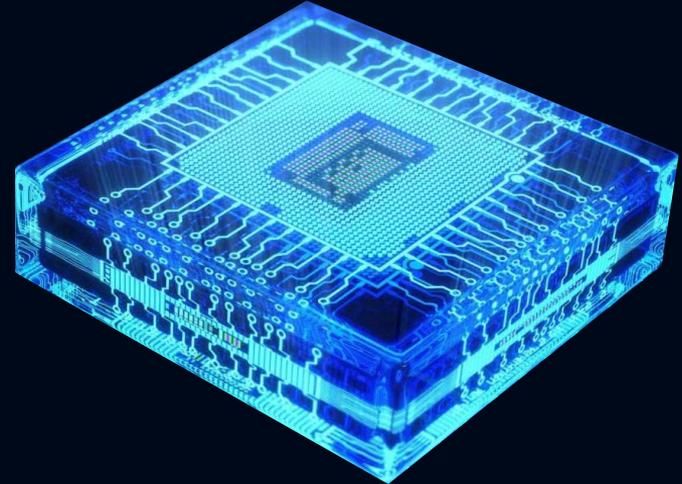
45%

Business Development:
Foundries & IDMs

11%

Let's Talk!

We're opening a **USD 2.7M pre-seed round** for partners wanting to shape the next-generation of interconnect materials.



Schedule a 30-min call
with us



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